ABSTRACT OF THE DISCLOSURE:

DICING FRAME

A dicing frame 1 is a hollow frame 1 that is formed by injection molding of resin-containing molding material for accommodating a semiconductor wafer therein and is removably vacuum-suctioned by vacuum suctioning pads 20. This dicing frame is formed with a spot facing portion 30 depressed in on the surface 4 of frame 1 and the surface 4 of frame 1 and the bottom surface 31 of spot facing portion 30 are joined by a slope 32 having an inclination angle of about 30 degrees or below.